

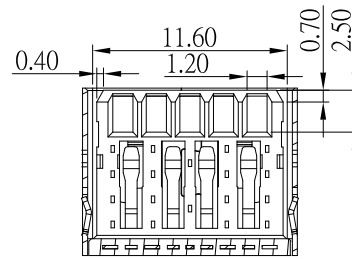
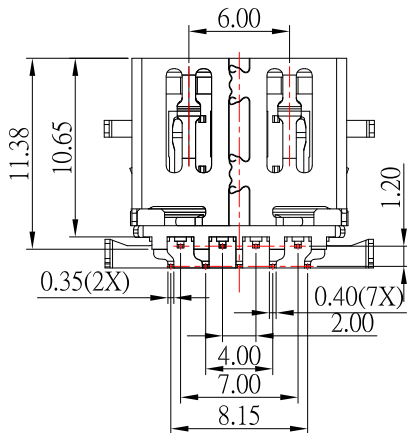
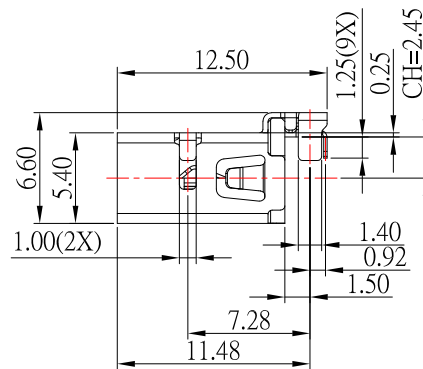
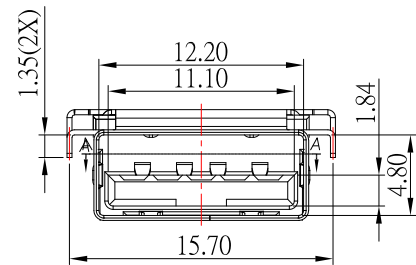
SUA-110E27-30xx-S277

鍍層厚度：

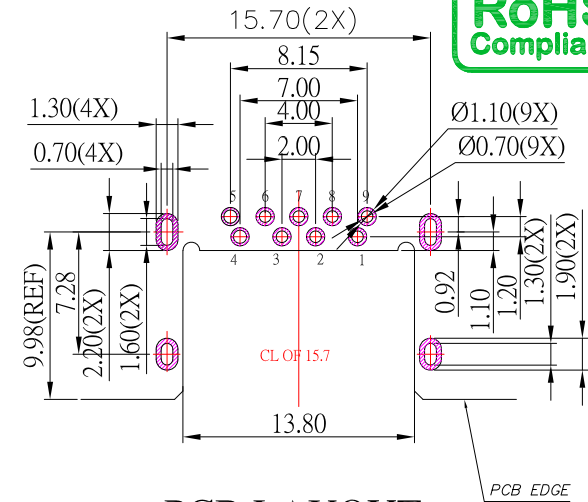
Blank : 1u"
2 : 15u"
3 : 30u"

HOUSING：

Blank : Blue
B : BLack



SECTION: A-A



PCB LAYOUT

NOTE:

1.MATERIAL:

1.1 Housing: LCP

1.2 Contact: Phosphor Bronze

1.3 Shell: SUS

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;

Tin Plated on Solder Balls ;

Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 Rate: 30V DC , 1.8 A

3.2 insulator Resistance:100MΩ Min

3.3 Dielectric Strength: 100V AC

3.4 Contact Resistance: 30mΩ Max

3.5 Operation Temperature: -55°C ~ +85°C

3.6 Insertion Force: 35 N

3.7 Extraction Force: 10 N

PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	DESCRIPTION
1	VBUS	POWER
2	D-	USB 2.0 DIFFERENTIAL PAIR
3	D+	
4	GND	GROUND FOR POWER RETURN
5	StdA-SSR-	SUPER-SPEED RECEIVER DIFFERENTIAL PAIR
6	StdA-SSR+	
7	GND-DRAIN	GROUND FOR SIGNAL RETURN
8	StdA-SST-	SUPER-SPEED TRANSMITTER DIFFERENTIAL PAIR
9	StdA-SST+	
SHELL	SHIELD	CONNECTOR METAL SHELL

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:

Jack Lu

DATE

01/08/26

MAT'L

TITLE

CONNECTOR

CHECKED BY:

Jacky Chen

DATE

01/08/26

FINISH

MODLE

USB AF 3.0反向無捲邊 DIP 沉板 ,CH2.45
板上H1.45mm

APPROVED BY:

Tony Kao

DATE

01/08/26

SCALE

1 : 1

DWG NO.

SUA-110E27-30xx-S277

SIZE

A4

VER

R

ITEM NO.	DESCRIPTION	DRAWN	DATE
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